



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



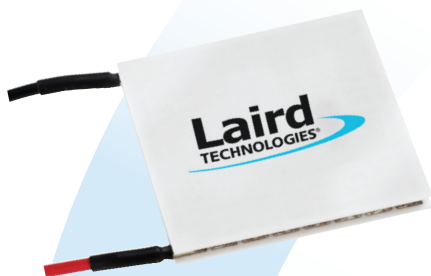
Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





The Ceramic Plate (CP) Series of Thermoelectric Modules (TEMs) is considered 'the standard' in the thermoelectric industry.

This broad product line of high-performance and highly reliable TEMs is available in numerous heat pumping capacities, geometric shapes, and input power ranges. Assembled with Bismuth Telluride semiconductor material and thermally conductive Aluminum Oxide ceramics, the CP Series is designed for higher current and large heat-pumping applications.

FEATURES

- Precise Temperature Control
- Compact Geometric Sizes
- Reliable Solid State Operation
- No Sound or Vibration
- Environmentally Friendly
- DC Operation
- RoHS Compliant

APPLICATIONS

- Medical Lasers
- Lab Science Instrumentation
- Clinical Diagnostic Systems
- Photonics Laser Systems
- Electronic Enclosure Cooling
- Food & Beverage Cooling
- Chillers (Liquid Cooling)

PERFORMANCE SPECIFICATIONS

Hot Side Temperature (°C)	25°C	50°C
Qmax (Watts)	80.9	88.8
Delta Tmax (°C)	67	75
I _{max} (Amps)	6.0	6.0
V _{max} (Volts)	22.7	25.7
Module Resistance (Ohms)	3.49	3.94

SUFFIX	THICKNESS (PRIOR TO TINNING)	FLATNESS & PARALLELISM	HOT FACE	COLD FACE	LEAD LENGTH
L1	0.150" ± 0.001"	0.001" / 0.001"	Lapped	Lapped	10"
L2	0.150" ± 0.0005"	0.0005" / 0.0005"	Lapped	Lapped	10"

SEALING OPTION

SUFFIX	SEALANT	COLOR	TEMP RANGE	DESCRIPTION
RT	RTV	White	-60 to 204 °C	Non-corrosive, silicone adhesive sealant
EP	Epoxy	Black	-55 to 150 °C	Low density syntactic foam epoxy encapsulant

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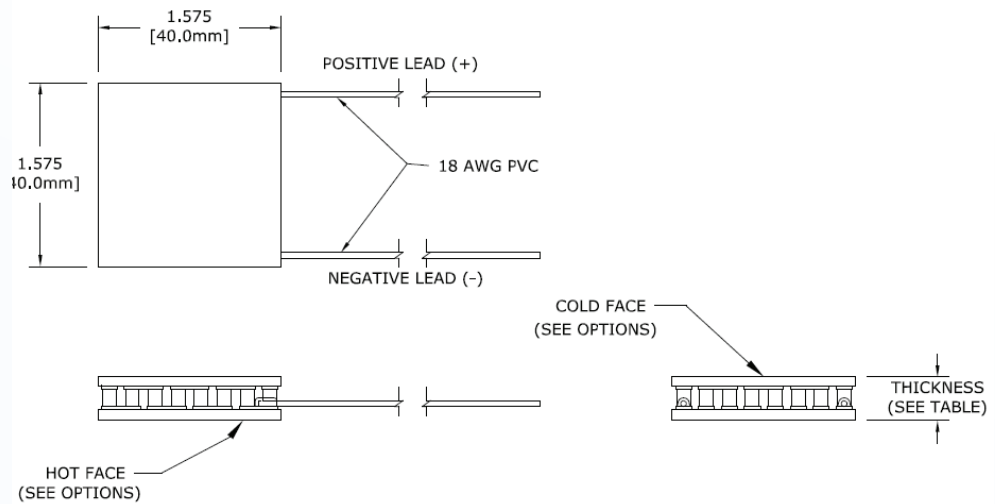
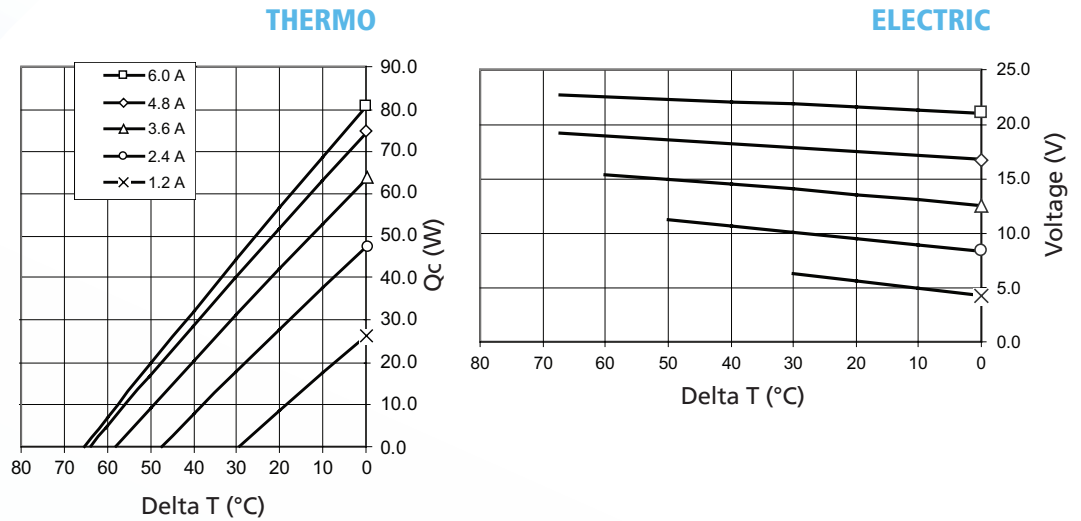
Europe: +46.31.420530

Asia: +86.755.2714.1166

clv.customerpos@lairdtech.com

www.lairdtech.com

Performance Curves at $T_h = 25^\circ\text{C}$



Ceramic Material: Alumina (Al_2O_3)
Solder Construction: 138°C, Bismuth Tin (BiSn)

OPERATING TIPS

- Max Operating Temperature: 80°C
- Do not exceed I_{max} or V_{max} when operating module
- Reference assembly guidelines for recommended installation
- Solder tinning also available on metallized ceramics

THR-DS-CP14,199,06 0812

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